

TinyLogic UHS Two-Input OR Gate

NC7SZ32

Description

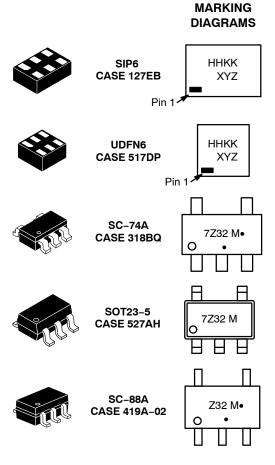
The NC7SZ32 is a single two-input OR gate from **onsemi's** Ultra–High Speed (UHS) series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra–high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and output are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V, independent of V_{CC} operating voltage.

Features

- Ultra-High Speed: $t_{PD} = 2.4 \text{ ns}$ (Typical) into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V_{CC}
- Power Down High-Impedance Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra-Small MicroPakTM Packages
- Space-Saving SOT23-5, SC-74A and SC-88A Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol



HH, 7Z32, Z32 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
M = Date Code

M = Date Code • = Pb-Free Package

(Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

Pin Configurations

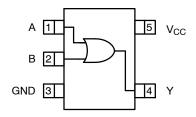


Figure 2. SOT23-5, SC-88A and SC-74A (Top View)

A 1 6 V_{CC} B 2 5 NC GND 3 4 Y

Figure 3. MicroPak (Top Through View)

PIN DEFINITIONS

Pin # SC-88A / SC74A/	"		
SOT23-5	Pin # MicroPak	Name	Description
1	1	Α	Input
2	2	В	Input
3	3	GND	Ground
4	4	Υ	Output
5	6	V _{CC}	Supply Voltage
	5	NC	No Connect

FUNCTION TABLE (Y = A + B)

Inp	Output	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	=	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	=	-50	mA
I _{OUT}	DC Output Current		=	±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		=	±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bias		-	+150	°C
TL	Junction Lead Temperature (Solde	ering, 10 Seconds)	=	+260	°C
P_{D}	Power Dissipation in Still Air	SC-74A / SOT23-5	=	390	mW
		SC-88A	-	332	
		MicroPak-6	=	812	
		MicroPak2™-6	-	812	
ESD	Human Body Model, JEDEC: JESD22-A114		=	4000	V
	Charge Device Model, JEDEC: JE	SD22-C101	=	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.50	5.50	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Times	V _{CC} = 1.8 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	
		V _{CC} = 5.0 V ±0.5 V	0	5	
$\theta_{\sf JA}$	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	
		MicroPak2-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

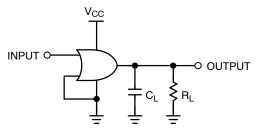
DC ELECTICAL CHARACTERISTICS

				T _A = +25°C		°C	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage	1.65 to 1.95		0.65 V _{CC}	_	-	0.65 V _{CC}	-	V
		2.30 to 5.50		0.70 V _{CC}	_	-	0.70 V _{CC}	-	1
V_{IL}	LOW Level Input Voltage	1.65 to 1.95		-	_	0.35 V _{CC}	-	0.35 V _{CC}	٧
		2.30 to 5.50		-	_	0.30 V _{CC}	-	0.30 V _{CC}	1
V _{OH}	HIGH Level Output Voltage	1.65	$V_{IN} = V_{IH}$ or V_{IL} ,	1.55	1.65	-	1.55	-	V
		1.80	I _{OH} = -100 μA	1.70	1.80	-	1.70	-	1
		2.30		2.20	2.30	-	2.20	-	1
		3.00		2.90	3.00	-	2.90	-	
		4.50		4.40	4.50	-	4.40	-	
		1.65	I _{OH} = -4 mA	1.29	1.52	-	1.29	-	1
		2.30	I _{OH} = -8 mA	1.90	2.15	-	1.90	-	1
		3.00	I _{OH} = -16 mA	2.40	2.80	-	2.40	-	1
		3.00	I _{OH} = -24 mA	2.30	2.68	-	2.30	_	
		4.50	I _{OH} = -32 mA	3.80	4.20	-	3.80	_	
V _{OL}	LOW Level Output Voltage	1.65	$V_{IN} = V_{IH} \text{ or } V_{IL},$	_	0.00	0.10	-	0.10	V
		1.80	I _{OL} = 100 μA	_	0.00	0.10	-	0.10	
		2.30		-	0.00	0.10	-	0.10	
		3.00		_	0.00	0.10	-	0.10	
		4.50		_	0.00	0.10	-	0.10	
		1.65	I _{OL} = 4 mA	-	0.80	0.24	-	0.24	
		2.30	I _{OL} = 8 mA	-	0.10	0.30	-	0.30	
		3.00	I _{OL} = 16 mA	_	0.15	0.40	-	0.40	
		3.00	I _{OL} = 24 mA	-	0.22	0.55	-	0.55	
		4.50	I _{OL} = 32 mA	_	0.22	0.55	-	0.55	
I _{IN}	Input Leakage Current	1.65 to 5.50	V _{IN} = 5.5 V, GND	-	-	±1	-	±10	μΑ
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} = 5.5 V	_	_	1	-	10	μΑ
I _{CC}	Quiescent Supply Current	1.65 to 5.50	V _{IN} = 5.5 V, GND	-	-	2.0	-	20	μΑ

AC ELECTRICAL CHARACTERISTICS

					Γ _A = +25°C	;	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay	1.65	C _L = 15 pF,	-	5.5	12.0	-	12.7	ns
	(Figure 4, 5)	1.80	$R_L = 1 M\Omega$	=	4.6	10.0	_	10.5	
		2.50 ±0.30		=	3.0	7.0	_	7.5	
		3.30 ±0.30		=	2.4	4.7	_	5.0	
		5.00 ±0.50		=	1.9	4.1	_	4.4	
		3.30 ±0.30	C _L = 50 pF,	_	3.0	5.2	_	5.5	
	$R_L = 500$	HL = 200 22	_	2.4	4.5	_	4.8		
C _{IN}	Input Capacitance	0.00		_	4	_	_	-	pF
C _{PD}	C _{PD} Power Dissipation Capacitance (Note 2) (Figure 6)	3.30		-	20	-	_	-	pF
		5.00		_	26	_	_	_	

C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).



NOTE:

C_L includes load and stray capacitance.
 Input PRR = 10 MHz, t_w = 500 ns

Figure 4. AC Test Circuit

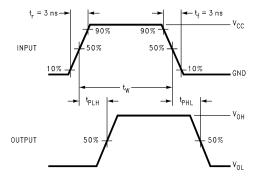
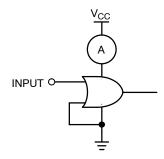


Figure 5. AC Waveforms



NOTE:

4. Input = AC Waveform; $t_r = t_f = 1.8$ ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I_{CC}D Test Circuit

ORDERING INFORMATION

Part Number	Top Mark	Packages	Shipping [†]
NC7SZ32M5X	7Z32	SC-74A	3000 / Tape & Reel
NC7SZ32P5X	Z32	SC-88A	3000 / Tape & Reel
NC7SZ32L6X	НН	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ32FHX	HH	UDFN6, MicroPak2	5000 / Tape & Reel

DISCONTINUED (Note 5)

NC7SZ32M5X-L22090	7Z32	SOT23-5	3000 / Tape & Reel
NC7SZ32P5X-F22057	Z32	SC-88A	3000 / Tape & Reel
NC7SZ32L6X-L22175	HH	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ32FHX-L22175	HH	UDFN6, MicroPak2	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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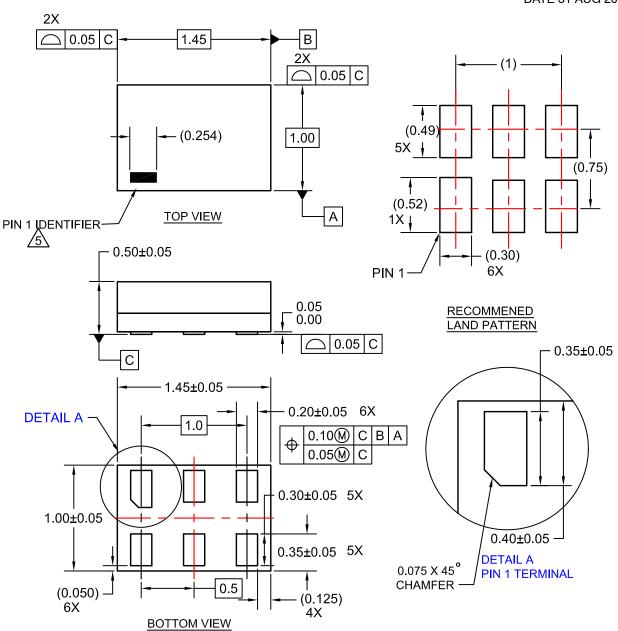


DISCONTINUED: These devices are not recommended for new design. Please contact your onsemi representative for information. The most current information on these devices may be available on www.onsemi.com.





DATE 31 AUG 2016



- NOTES:
- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4.PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
 - OTHER LINE IN THE MARK CODE LAYOUT.

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DESCRIPTION:	SIP6 1.45X1.0		PAGE 1 OF 1	

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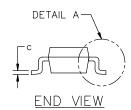


SC-74A-5 3.00x1.50x0.95, 0.95P CASE 318BQ ISSUE C

DATE 26 FEB 2024

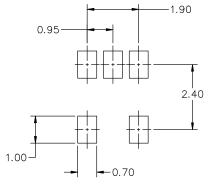


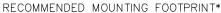
- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.



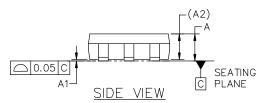
DIM					
DIN	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0.01	0.18	0.10		
A2	(0.95 REF			
Ь	0.25	0.37	0.50		
C	0.10	0.18	0.26		
D	2.85	3.00	3.15		
E	:	2.75 BSC	;		
E1	1.35	1.50	1.65		
е	(0.95 BSC	;		
L	0.20	0.40	0.60		
L1	0.62 REF.				
L2	0.25 BSC				
Θ	0,	5°	10°		

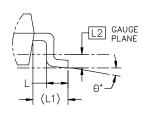
MILLIMETERS





* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.





DETAIL "A" SCALE 2:1

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

DESCRIPTION:	SC-74A-5 3.00x1.50x0.95,	0.95P	PAGE 1 OF 1
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SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

DATE 11 APR 2023

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS
- 419A-01 DBSDLETE, NEW STANDARD 419A-02
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,

DIM	MILLIMETERS			
INITU	MIN.	N□M.	MAX.	
А	0.80	0.95	1.10	
A1			0.10	
A3	0.20 REF			
b	0.10	0.20	0.30	
C	0.10		0.25	
D	1.80	2.00	2,20	
Е	2.00	2.10	2.20	
E1	1.15	1.25	1.35	
е	0.65 BSC			
L	0.10	0.15	0.30	

5X b

→ 0.2 M B M

- PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

	L → 	
<u> </u>	0.50	5

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

5. COLLECTOR

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. ANODE	PIN 1. ANODE 1	PIN 1. SOURCE 1	PIN 1. CATHODE
2. EMITTER	2. EMITTER	2. N/C	2. DRAIN 1/2	2. COMMON ANODE
3. BASE	3. BASE	3. ANODE 2	SOURCE 1	3. CATHODE 2
4. COLLECTOR	COLLECTOR	CATHODE 2	4. GATE 1	4. CATHODE 3
COLLECTOR	CATHODE	CATHODE 1	5. GATE 2	5. CATHODE 4
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	Note: Please refer to datasheet for
PIN 1. EMITTER 2	PIN 1. BASE	PIN 1. CATHODE	PIN 1. ANODE	atula callout. If atula tupa is not called
2. BASE 2	2. EMITTER	2. COLLECTOR	2. CATHODE	style callout. If style type is not called
EMITTER 1	3. BASE	3. N/C	3. ANODE	out in the datasheet refer to the device
4. COLLECTOR	COLLECTOR	4. BASE	4. ANODE	datasheet pinout or pin assignment.
COLLECTOR 2/BASE 1	5. COLLECTOR	5. EMITTER	5. ANODE	datasheet pinout of pin assignment.

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DESCRIPTION:	SC-88A (SC-70-5/SOT-35	53)	PAGE 1 OF 1	

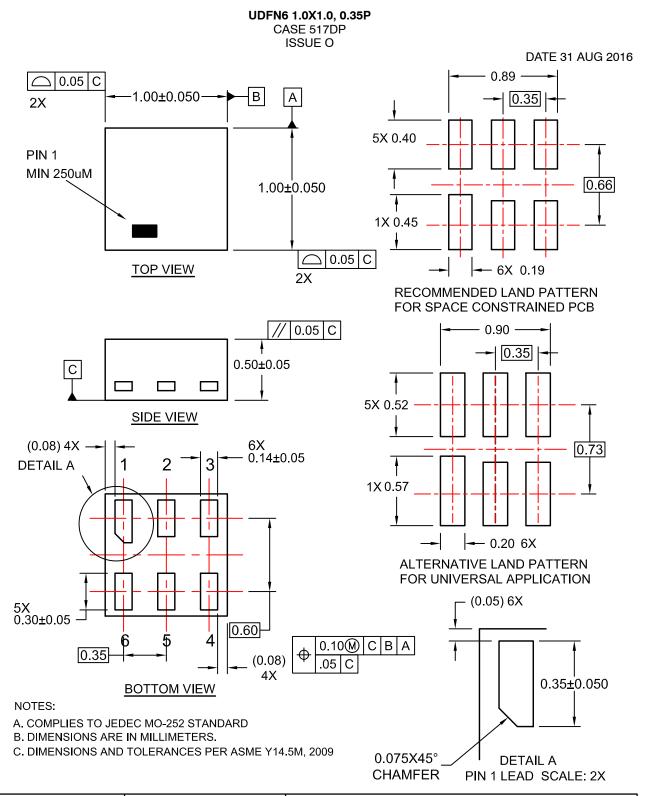
5. EMITTER

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5. COLLECTOR 2/BASE 1





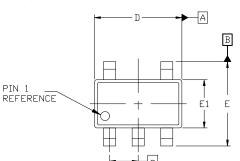


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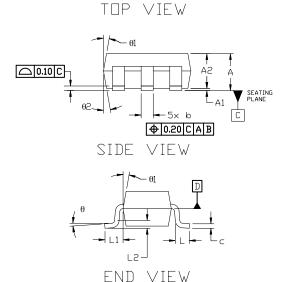


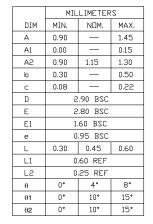
SOT-23, 5 Lead CASE 527AH ISSUE A

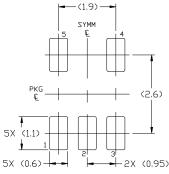
DATE 09 JUN 2021

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED O. 25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION '6' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE O.O8mm TOTAL IN EXCESS OF THE '6' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN O.O7mm.







GENERIC MARKING DIAGRAM*



XXX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDL DERRM/D.

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DESCRIPTION:	SOT-23, 5 LEAD		PAGE 1 OF 1	

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